



REMARKS

Claims 1 to 20 have initially been canceled, claim 26 is now canceled, claims 21, 22 and 27 have been amended and claim 29 to 35 have been added for the purpose of having an interference declared. Claims 21 to 25 and 27 to 35 are now active in this application. Please charge any cost to Deposit Account No. 20-0668.

Claims 21 to 23 and 25 to 28 were rejected under 35 U.S.C. 102(e) as being anticipated by Holman (U.S.6,005,776). The rejection is respectfully traversed.

Claim 21 has been amended by adding thereto the acute angle portion of claim 27. All of the claims not copied from Patent No. 6,418,033 now require the step of electrically connecting the at least one electrical terminal on the at least one edge surface of the integrated circuit package to the top surface of the printed circuit board at an acute angle with the top surface of the printed circuit board. This claim is drawn to the one of the embodiments previously claimed as shown in Fig. 7 and includes only the integrated circuit packages which are disposed at an acute angle to the top surface of the printed circuit board. Prior claim 27 included this feature as well as the perpendicular feature, the latter feature now having been canceled. No such feature is taught or suggested by any of the applied references and clearly not by Holman.

Claims 22 to 25, 27 and 28 depend from claim 21 and therefore define patentably over Holman for at least the reasons set forth above with reference to claim 21.

In addition, claim 22 further limits claim 21 by requiring the step of electrically and perpendicularly connecting at least two integrated circuit packages to the circuit board. No such combination is taught or suggested by Holman.

Claim 23 further limits claim 21 by requiring the step of disposing a solder ball between the side surface terminal of the integrated circuit package and the top of the circuit board. No such combination is taught or suggested by Holman.

Claim 25 further limits claim 21 by requiring the step of integrally attaching at least three tabs to said circuit board. No such combination is taught or suggested by Holman.

Claim 27 further limits claim 21 by requiring that the integrated circuit package be further defined as being connected at an acute angle between 30 and less than 90 degrees to the circuit board. No such feature is is taught or suggested by Holman either alone or in the combination as claimed..

Claim 28 further limits claim 21 by requiring that the at least one edge surface is four edge surfaces, each of the four edge surfaces disposed between the major surfaces to form a closed package with the major surfaces. No such combination is taught or suggested by Holman.

Claim 24 was rejected under 35 U.S.C. 103(a) as being unpatentable over Holman in view of Dockerty et al (U.S. 6,395,991). The rejection is respectfully traversed.

Claim 24 further limits claim 21 by requiring the step of disposing solder columns between the integrated circuit and the top of the circuit board. Dockerty fails to overcome the deficiencies in Holman as noted above with reference to claim 21. It follows that no such combination is taught or suggested by Holman, Dockerty or any proper combination of these references.

Claims 29 to 35 are claims 1 to 6 and 9 respectively of Patent No. 6,418,033 of Glenn A. Rinne and are copied for the purpose of having an interference declared. Other

claims of Rinne et al. can also be made, but will be added as coming under the count or counts in the event an interference is declared, if not by the Examiner then by way of motion.

In accordance with the requirements of 37 C.F.R.1.607, the following facts are presented:

1. The patent with which it is requested that an interference be declared is Patent No. 6,418,033 of Rinne.

2. A proposed count would read as follows:

“A microelectronic package comprising:
a first microelectronic substrate;
a second microelectronic substrate that is oriented at an acute angle relative to the first microelectronic substrate; and
a plurality of solder bumps between the first and second microelectronic substrates, adjacent an edge of the second microelectronic substrate, that directly connect the second microelectronic substrate to the first microelectronic substrate and that are confined to within the edge of the second microelectronic substrate.”

3. The above proposed count is claim 1 of Patent No. 6, 418,033.

4. The above count is claim 29 as above added. In addition, claim 27 prior to amendment herein was originally filed (erroneously numbered 28 originally) in parent application Serial No. 09/115,565 which predated even the filing date of Rinne.

5. The proposed count is presumed to be readable on Rinne Patent No. 6,418,033 since it is taken from that patent and is readable on the subject disclosure as follows:

A microelectronic package comprising:
a first microelectronic substrate (160 of Fig. 7);
a second microelectronic substrate that is oriented at an acute angle relative to the first microelectronic substrate (integrated circuits 30,32 in Fig. 7 which are disposed at an acute angle and the embodiments of integrated circuit 30,32 in Figs. 8B and 8C); and
a plurality of solder bumps (150 in Fig. 7) between the first and second microelectronic substrates, adjacent an edge of the second microelectronic substrate, that directly connect the second microelectronic substrate to the first microelectronic substrate and that are confined to within the edge of the second microelectronic substrate.

6. The requirements of 35 U.S.C.135(b) are met because the acute angle features was claimed in the parent application ab initio in claim 27 (originally designated claim 28).

The requirements of 37 C.F.R. 1.608 do not apply since the subject application would be the senior party based upon the fact that this application is a division of Serial No. 09/478,917, which is a division of Serial No. 09/115,567, which claims priority from Singapore application Serial No. 9800174-6, filed January 23, 1998.

In view of the above remarks, favorable reconsideration and declaration of an interference are respectfully requested.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'J. Cantor', is written over the typed name.

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